# The RF Line NPN Silicon RF Power Transistors

... designed for 24 volt UHF large-signal, common-emitter amplifier applications in industrial and commercial FM equipment operating in the range of 800-960 MHz.

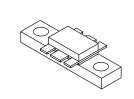
- Specified 24 Volt, 900 MHz Characteristics
  - Output Power = 5.0 Watts Power Gain = 9.0 dB Min Efficiency = 50% Min
- Series Equivalent Large-Signal Characterization
- Capable of Withstanding 20:1 VSWR Load Mismatch at Rated Output Power and Supply Voltage
- Gold Metallized, Emitter Ballasted for Long Life and Resistance to Metal Migration
- · Silicon Nitride Passivated
- Circuit board photomaster available upon request by contacting RF Tactical Marketing in Phoenix, AZ.

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCEO	30	Vdc
Collector–Emitter Voltage	VCES	55	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	4.0	Vdc
Collector Current — Continuous	IC	0.6	Adc
Total Device Dissipation @ T <sub>A</sub> = 50°C (1) Derate above 50°C	PD	18 0.143	Watts W/°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C

# MRF891 MRF891S

5.0 W, 900 MHz RF POWER TRANSISTORS NPN SILICON



CASE 319-07, STYLE 2 MRF891



CASE 319A-02, STYLE 2 MRF891S

## THERMAL CHARACTERISTICS

 $(I_C = 200 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc})$ 

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case (2)	$R_{\theta JC}$	7.0	°C/W

# **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•				
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = 20 mAdc, I <sub>B</sub> = 0)	V(BR)CEO	30	_	_	Vdc
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = 20 mAdc, V <sub>BE</sub> = 0)	V(BR)CES	55	_	_	Vdc
Emitter–Base Breakdown Voltage (I <sub>E</sub> = 0.5 mAdc, I <sub>C</sub> = 0)	V(BR)EBO	4.0	_	_	Vdc
Collector Cutoff Current (V <sub>CE</sub> = 30 Vdc, V <sub>BE</sub> = 0, T <sub>C</sub> = 25°C)	ICES	_	_	1.0	mAdc
ON CHARACTERISTICS					
DC Current Gain	hFF	30	_	150	

NOTES:

(continued)

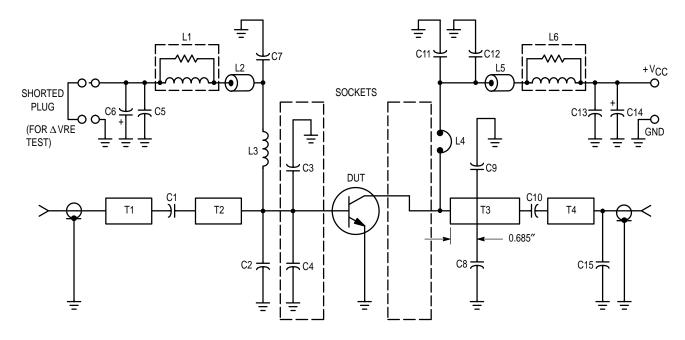
- 1. This device is designed for RF operation. The total device dissipation rating applies only when the device is operated as an RF amplifier.
- 2. Thermal Resistance is determined under specified RF operating conditions by infrared measurement techniques.

#### REV 6



# **ELECTRICAL CHARACTERISTICS** — **continued** $(T_C = 25^{\circ}C)$ unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
DYNAMIC CHARACTERISTICS					
Output Capacitance (V <sub>CB</sub> = 24 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>ob</sub>	_	6.5	8.0	pF
FUNCTIONAL TESTS					
Common–Emitter Amplifier Power Gain (Broadband) (V <sub>CC</sub> = 24 Vdc, P <sub>Out</sub> = 5.0 W, f = 900 MHz)	G <sub>pe</sub>	9.0	10	_	dB
Collector Efficiency (V <sub>CC</sub> = 24 Vdc, P <sub>Out</sub> = 5.0 W, f = 900 MHz)	η	50	57	_	%
Load Mismatch Stress (V <sub>CC</sub> = 24 Vdc, P <sub>in</sub> = 0.63 W, f = 900 MHz, VSWR = 20:1, all phase angles)	Ψ	No Degradation in Output Power			



C1 — 39 pF, 100 Mil Chip Capacitor

C2, C8, C15 — 0.8-8.0 pF Johansen Gigatrim

C3, C4 — 12 pF, Mini–Unelco

C5, C13 — 1000 pF, 350 V Unelco

C6, C14 — 10  $\mu$ F, 25 V Tantalum

C7, C11, C12 — 91 pF, Mini-Unelco

C9 — 5.0 pF, MIni–Unelco

C10 — 47 pF, 100 Mil Chip Capacitor

L1, L6 — 10 Turns #20 AWG Around 10 Ohm 1/2 Watt Resistor

L2, L5 — Ferrite Bead

L3 — 4 Turns #16 AWG Choke

L4 — 0.5", #18 AWG Wire

T1, T4 — 50 Ohm Microstrip Line

T2 — W = 165 Mils,  $\ell$  = 1946 Mils

T3 — W = 166 Mils,  $\ell$  = 1563 Mils

PC Board — 0.031" Glass Teflon ( $\epsilon_{\text{r}}$  = 2.56)

Figure 1. Broadband Test Fixture

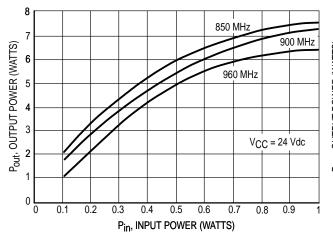


Figure 2. Output Power versus Input Power

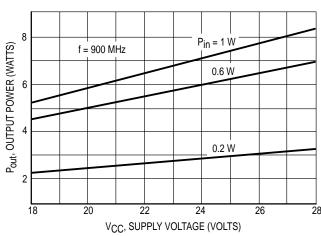


Figure 3. Output Power versus Supply Voltage

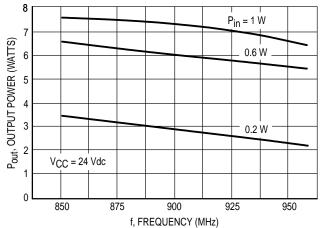


Figure 4. Output Power versus Frequency

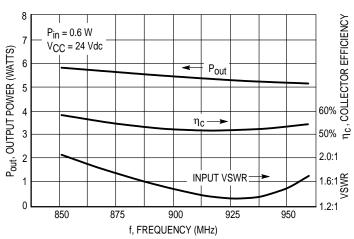


Figure 5. Typical Broadband Circuit Performance

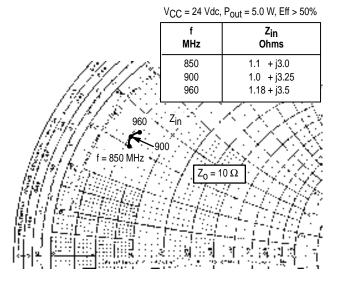


Figure 6. Series Equivalent Input Impedance

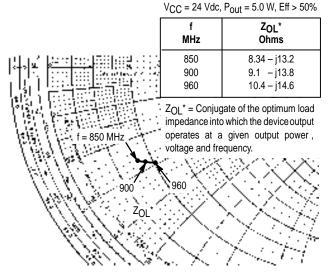
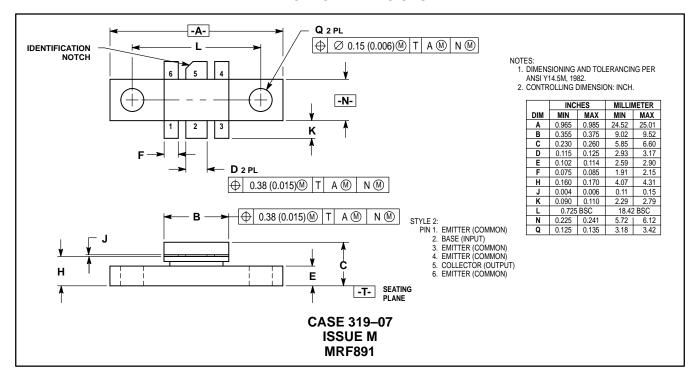
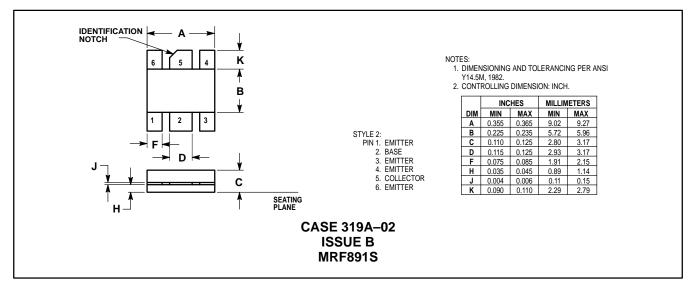


Figure 7. Series Equivalent Output Impedance

MOTOROLA RF DEVICE DATA MRF891 MRF891S

## PACKAGE DIMENSIONS





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